

J. A.  
SCARLETT

The  
Multilayer  
Printed  
Circuit Board  
Handbook

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# THE MULTILAYER PRINTED CIRCUIT BOARD HANDBOOK

*Edited by*  
**J. A. SCARLETT**

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## CONTENTS

	PREFACE	v
	CHAPTER ONE	
	<b>Introduction</b>	
	<i>J. A. Scarlett</i>	
1.1	General	1
1.1.1	Printed Circuit Boards	1
1.1.2	History	2
1.1.3	The Electrical Importance of Multilayer Boards	3
1.1.4	Costs and Applications	3
1.1.4.1	Costs of Boards	3
1.1.4.2	Costs of Alternatives to Boards	5
1.1.4.3	Choice of Board Type	6
1.1.4.4	Thermal Problems	7
1.1.4.5	System Architecture and Board Type	8
1.1.4.6	Probable Need for Multilayers	9
1.2	Types of Multilayer Board	11
1.2.1	Access Hole Boards	11
1.2.1.1	Access Hole Boards with Internal Connections	12
1.2.1.2	Disadvantages of Access Hole Boards	14
1.2.1.3	Solder Buttons	14
1.2.2	Plated Pillar Boards	15
1.2.3	Staked Boards	16
1.2.4	Bonded Through-hole Plated Boards	16
1.2.5	Buried Via-hole Boards	17
1.2.6	Sequential Buried Via-hole Boards	18
1.2.6.1	Two-level Buried Via Holes	18
1.2.6.2	Multiple Level Buried Via Holes	18
1.2.7	Double-double Boards	19
1.2.8	Double-multilayer Boards	19
1.2.9	Flexi-rigid Boards	20
1.2.10	Other Forms of Multilayer Interconnects	20
1.2.10.1	Etched and Welded Interconnects	20
1.2.10.2	Three Dimensional Planar Co-axial Interconnects	21
1.2.10.3	Etched and Filled Boards	22
1.2.10.4	Moulded Boards	22
1.2.10.5	Multiwire	23
1.3	Production of Through-hole Plated Multilayers	23
1.3.1	General	23
1.3.2	Preparation of Inner Layers	24
1.3.2.1	Film Work	24
1.3.2.1.1	Incoming Photo Tools	24
1.3.2.1.2	Film Types and Labels	25
1.3.2.1.3	Step and Repeat	27
1.3.2.1.4	Borders	28
1.3.2.1.5	Environmental Control	29

1.3.2.1.6	Film Punching	30
1.3.2.2	Planning	33
1.3.2.3	Tape Making	33
1.3.2.4	Laminate Preparation	34
1.3.2.5	Inner Layer Printing and Etching	34
1.3.2.6	Preparation for Bonding	34
1.3.3	Bonding	38
1.3.4	Drilling	38
1.3.5	Smear Removal	38
1.3.6	Through-hole Plating and Outer Layers	41
1.3.7	Finishing	41
1.4	Production Variants	41
1.4.1	Pillar Plated Boards	41
1.4.2	Buried Via-hole Boards	42
1.4.2.1	Inner Layer Plating	42
1.4.2.2	Lay Up and Bonding	44
1.4.2.3	Pre-filling of Buried Holes	44
1.4.3	Sequential Buried Via Holes	45
1.4.4	Double Boards	45
1.4.5	Flexi-rigids	45
1.4.6	Mass Lamination	46
1.4.7	Semi-additive Multilayers	46
1.4.8	Bonding of Heat Ladders	46
1.5	Build and Thickness	48
1.5.1	Prepreg Layers	48
1.5.2	Board Thickness	49
1.5.3	Practical Builds	50
1.5.3.1	Four Layer Boards	50
1.5.3.2	Higher Build Boards	50
1.5.3.3	Buried Via-hole and Flexi-rigid Builds	52
1.6	Handling Thin Laminates	52
1.6.1	Storage and Transport	53
1.6.2	Cutting	53
1.6.3	Picking Up Thin Laminates	53
1.6.4	Conveyorised Machines	54
1.6.5	Plating Fixtures	54
1.7	Reliability of Multilayer Boards	54
1.7.1	Delamination	55
1.7.2	Outgassing	55
1.7.3	Short Circuits	56
1.7.3.1	Design and Manufacturing Faults	56
1.7.3.2	Growth of Short Circuits	56
1.7.4	Carbonisation	58
1.7.5	Warping	58
1.7.6	Damage to Through-plated Holes	58
1.7.6.1	Mechanical Damage	58
1.7.6.2	Z-Plane Expansion	59

## CHAPTER TWO

**Laminates and Prepregs***J. S. Sallo*

2.1	Introduction	61
2.1.1	Use of Epoxy Materials in Laminate and Prepreg Manufacture	61

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